PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data	
1.1 Company	STMicroelectronics International N.V
1.2 PCN No.	EMBEDDED PROCESSING/26/16574
1.3 Title of PCN	HTXA subcontractor (China) additional back-end qualification for 2Kb to 128Kb I²C EEPROM in DFN8
1.4 Product Category	2Kb to 128Kb CMOSF8H+ I²C EEPROM in DFN8
1.5 Issue date	2026-09-06

2. PCN Team	
2.1 Contact supplier	
2.1.1 Name	RAHIL BASSEL
2.1.2 Phone	
2.1.3 Email	bassel.rahil01@st.com
2.2 Change responsibility	
2.2.1 Product Manager	David RICHETTO
2.1.2 Marketing Manager	Sylvain FIDELIS
2.1.3 Quality Manager	Mickael DENAIS-ALLICHON

3. Change		
3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Transfer	Transfer from one site to another site: Warehouse, hub including electronic data transfer (Inkless maps, PT data, STDF…), (SOP 2617)	NA

4. Description of change		
	Old	New
4.1 Description	The low densities EEPROM I²C 2Kb to 128Kb in DFN8 (CMOS F8H+ process technology) currently assembled & tested at ST Calamba (Philippines)...	...will also be assembled & tested at HTXA subcontractor (China).
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	- Form: Marking change - Fit: No change - Function: No change	

5. Reason / motivation for change	
5.1 Motivation	The strategy of STMicroelectronics Connected Security division is to support our customers on products and service quality on a long-term basis. In line with this commitment, the qualification of the HTXA back-end assembly & test site as a second source will allow us to increase capacity and reinforce long term competitiveness.
5.2 Customer Benefit	DOUBLE SOURCING

6. Marking of parts / traceability of change	
6.1 Description	Assembly plant identifier “U” on DFN8 package.

7. Timing / schedule	
7.1 Date of qualification results	2026-10-19
7.2 Intended start of delivery	2026-11-30
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation			
8.1 Description	16574 Preliminary Reliability Report RRCS2610 - F8HP4 DFN8 HTXA.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2026-09-06

9. Attachments (additional documentations)
16574 Public product.pdf 16574 PCN DFN8 @HTXA.pdf 16574 Preliminary Reliability Report RRCS2610 - F8HP4 DFN8 HTXA.pdf

10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	M24128-BFMC6TG	
	M24C02-FMC6TG	
	M24C02-RMC6TG	
	M24C04-FMC6TG	
	M24C08-FMC6TG	
	M24C08-RMC6TG	
	M24C16-FMC6TG	
	M24C16-RMC6TG	
	M24C32-FMC6TG	
	M24C64-FMC6TG	

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Public Products List

Publict Products are off the shelf products. They are not dedicated to specific customers, they are available through ST Sales team, or Distributors, and visible on ST.com

PCN Title : HTXA subcontractor (China) additional back-end qualification for 2Kb to 128Kb I²C EEPROM in DFN8

PCN Reference : EMBEDDED PROCESSING/26/16574

Subject : Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.

M24C32-FMC6TG	M24C08-RMC6TG	M24C02-RMC6TG
M24C04-FMC6TG	M24128-BFMC6TG	M24C02-FMC6TG
M24C64-FMC6TG	M24C04-RMC6TG	M24C16-RMC6TG
M24C08-FMC6TG	M24C16-FMC6TG	

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Preliminary Reliability Report

RRCS2610

New Back End site qualification

F8HP4 DFN8 HTXA

General Information	
Commercial Product	M24C02-FMC6TG M24C02-RMC6TG M24C04-FMC6TG M24C04-RMC6TG M24C08-FMC6TG M24C08-RMC6TG M24C16-FMC6TG M24C16-RMC6TG M24C32-FMC6TG M24C32-FMC6TG/T M24C64-FMC6TG M24128-BFMC6TG M24128-BFMC6TG/T
Product Line	3FE41T, 24081T, 24161T, 24321T, 24641T, 24281T
Package	UFDFPN 2x3x0.6 8L 0.5MM
Silicon Technology	CMOSF8H4

Traceability	
Diffusion Plant	Rousset 8
Assembly Plant	HTXA - China

Reliability Assessment	
Pass	
Fail	

Release	Date	Author	Function
1.0	August 31st 2026	Christèle Marmugi	Connected Security BE Quality Engineer

DOCUMENT ACTORS:

Name	Function	Location	Date
Olivier Vallier	Connected Security Product Reliability & Qualification Quality Engineer	Rousset	August 31st 2026
Christèle MARMUGI	Connected Security BE Quality Engineer	Rousset	August 31st 2026
Michel DERIE	Connected Security BE Quality Manager	Rousset	August 31st 2026

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RELIABILITY EVALUATION OVERVIEW

- **OBJECTIVE**

The objective of this intermediate reliability report is to present first reliability results of the qualification regarding the new back end assembly site HTXA for F8HP4 EERPOM ICs technology in DFN8 package.
The scope of this reliability report is F8HP4 EEPROM ICs technology product with memory size from 2k to 128k assembled in DFN8 package

- **CONCLUSION**

First reliability tests have been completed with positive results. Neither functional nor parametric rejects were detected at final electrical testing.
Package oriented tests have not put in evidence any criticality.

Based on these first results obtained, F8HP4 products diffused in Rousset Fab and assembled in DFN8 at HTXA plant have positively passed first phase of reliability evaluation. Biased stress and physical analysis are still ongoing.

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1. RELIABILITY STRATEGY

Reliability evaluation is based on the standard STMicroelectronics corporate procedures for quality and reliability, namely RELIABILITY TESTS AND CRITERIA FOR QUALIFICATION, and in compliance with the JESD-47L international standard.

The following qualification strategy has been defined:
• Package reliability evaluation on 6 assembly lots (3 lots of 8k and 3 lots of 128k) of F8H technology.

Reliability trials performed as part of this reliability evaluation are listed in test results summary in section 3, including specifications references

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2. PRODUCT OR TEST VEHICLE CHARACTERISTICS

2.1. Generalities

The reliability evaluation is based on 3 lots of F8HP4 8K product in DFN8 and 3 lots of F8HP4 128K product in DFN8 which support small and large sizes of F8HP4 dies.

2.2. Traceability

2.2.1. Wafer Fab Information

Main die - S24081TA

Wafer Fab Information	
FAB1	
Wafer fab name / location	ST SAS Rousset / Rousset 8
Wafer diameter (inches)	8
Wafer thickness (µm)	280
Silicon process technology	CMOSF8H4
Die finishing front side (passivation) materials	USG NitUV (HFP USG UV Nitride)
Die finishing back side Materials	RAW SILICON - BACK GRINDING
Die area (Stepping die size)	494, 604
Sawing street width (X,Y) (µm)	60,80

Main die - S24281TA

Wafer Fab Information	
FAB1	
Wafer fab name / location	ST SAS Rousset / Rousset 8
Wafer diameter (inches)	8
Wafer thickness (µm)	280
Silicon process technology	CMOSF8H4
Die finishing front side (passivation) materials	USG NitUV (HFP USG UV Nitride)
Die finishing back side Materials	RAW SILICON - BACK GRINDING
Die area (Stepping die size)	968, 856
Sawing street width (X,Y) (µm)	60,80

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2.2.2. Assembly Information

Assembly Information	
Package 1:UFDFPN 2x3x0.6 8L 0.5MM PITCH	
Assembly plant name / location	HTXA / HTXA - China
Die thickness after back-grinding (µm)	180µ
Die sawing method	Mechanical
Lead frame/Substrate material/supplier/reference	DFN8L(0203x055-0.50) XHH
Lead frame finishing (material)	Matte Sn plating
Die attach material/ supplier	HITACHI EN4900GC
Wire bonding material/diameter	WIRE CuPd 0.8mil
Molding compound material/supplier/reference	EME-G770HCD-M SUMITOMO
Package Moisture Sensitivity Level (JEDEC J-STD020D)	MSL1

2.2.3. Reliability testing information

Reliability Testing Information	
Reliability laboratory name / location	Grenoble Rel Lab, Rousset MDG Rel Lab, HTXA Rel Lab

Note: ST is ISO 9001 certified. This induces certification of all internal and subcontractor labs. ST certification document can be downloaded under the following link: http://www.st.com/content/st_com/en/support/quality-and-reliability/certifications.html

3. TEST RESULTS SUMMARY

3.1. Lot information

Lot #	Diffusion Lot	Assy Lot / Trace Code	Raw Line	Package
Lot 1	VG545873	CC06040002 / GU623002	XAZW*2408RTA	DFN8
Lot 2	VG549884	CC06040007 / GU623005	XAZW*2408RTA	DFN8
Lot 3	VG551148	CC06040006 / GU623006	XAZW*2408RTA	DFN8
Lot 4	VG604596	CC06040005 / GU623003	XAZW*2428FTA	DFN8
Lot 5	VG604504	CC06040003 / GU623004	XAZW*2428FTA	DFN8
Lot 6	VG604597	CC06040001 / GU623001	XAZW*2428FTA	DFN8

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3.2. Test plan and results summary

ACCELERATED ENVIRONMENT STRESS TESTS

Test code	Stress method	Stress Conditions	Lots Qty	S.S.	Total	Results/Lot Fail/S.S.	Comments:(N/A =Not Applicable)
PC	J-STD-020	24h bake@125°C MSL1 (168h@85°C/85%RH) 3x Reflow simulation Peak Reflow Temp= 260°C ☒ Testing at Room T°	6	154	924	Lot 1 : 0/154 Lot 2 : 0/154 Lot 3 : 0/154 Lot 4 : 0/154 Lot 5 : 0/154 Lot 6 : 0/154	PASS
HTSL	JESD22-A103	Ta= 150°C Duration= 1000h ☒ Testing at Room T°	6	77	462	Lot 1 : 0/77 Lot 2 : 0/77 Lot 3 : 0/77 Lot 4 : 0/77 Lot 5 : 0/77 Lot 6 : 0/77	PASS
TC	JESD22-A104	Ta= -65 / +150°C, 2cy/h Duration = 500cy ☒ After PC ☒ Testing at Room T°	6	77	462	Lot 1 : 0/77 Lot 2 : 0/77 Lot 3 : 0/77 Lot 4 : 0/77 Lot 5 : 0/77 Lot 6 : 0/77	PASS
UHAST	JESD22-A118	Ta=130°C/85%RH Duration= 96h ☒ After PC ☒ Testing at Room T°	6	77	462	Lot 1 : 0/77 Lot 2 : 0/77 Lot 3 : 0/77 Lot 4 : 0/77 Lot 5 : 0/77 Lot 6 : 0/77	PASS
PC	J-STD-020	24h bake@125°C, 3x Reflow simulation Peak Reflow Temp= 260°C	6	77	462	Lot 1 : 0/77 Lot 2 : 0/77 Lot 3 : 0/77 Lot 4 : 0/77 Lot 5 : 0/77 Lot 6 : 0/77	PASS
HAST	JESD22-A110	Ta=130°C/85%RH with bias Duration= 96hrs ☒ After PC ☒ Testing at Room T°	6	77	462	Lot 1 : 0/77 Lot 2 : 0/77 Lot 3 : 0/77 Lot 4 : 0/77 Lot 5 : 0/77 Lot 6 : W39	On going, due W39

Electrical Verification Tests

Test code	Stress method	Stress Conditions	Lots Qty	S.S.	Total	Results/Lot Fail/S.S.	Comments:(N/A =Not Applicable)
CDM	JEDEC JS-002	Target CDM= 500V ☒ Testing at Room	2	3 per voltage	6	Lot 1 : Lot 6 :	On going, due W39

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PACKAGE ASSEMBLY INTEGRITY TESTS

Test	Reference	Test Conditions	Lots Qty	S.S.	Total	Results/Lot Fail/S.S.	Comments(N/A =Not Applicable)
WBS	JESD22-B116B	Equipment: MFM1200/ T-480 Sampling: 30 wires / 5 units	6	30 wires	180 bonds	Lot 1: 0/30 Lot 2: 0/30 Lot 3: 0/30 Lot 4: 0/30 Lot 5: 0/30 Lot 6: 0/30	PASS
WBP	Mil-STD-883, Method 2011	Equipment: MFM1200 /T-482 Sampling: 3 wires / unit	6	30 wires	180 bonds	Lot 1: 0/30 Lot 2: 0/30 Lot 3: 0/30 Lot 4: 0/30 Lot 5: 0/30 Lot 6: 0/30	PASS
SD	JESD22 B102 JSTD-002D	Solder Bath,2 conditions tested Solder: SnAgCu Aging ☒Steam aging 85°C/85%RH ☒Dry Air 150°C	6	10 units per condition and per lot	120	Lot 1: 0/20 Lot 2: 0/20 Lot 3: 0/20 Lot 4: 0/20 Lot 5: 0/20 Lot 6: 0/20	PASS
PD	JESD22 B100, JESD22 B108	Physical Dimensions Construction Analysis Optical microscopy	6	10	60	Lot 1: 0/10 Lot 2: 0/10 Lot 3: 0/10 Lot 4: 0/10 Lot 5: 0/10 Lot 6: 0/10	On going, due W39

Note: Test method revision reference is the one active at the date of reliability trial execution.

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4. APPLICABLE AND REFERENCE DOCUMENTS

Remove from below list not applicable documents.

Reference	Short description
JESD47	Stress-Test-Driven Qualification of Integrated Circuits

5. GLOSSARY

CDM	Electrostatic Discharge - Charged device model
HAST	Biased HAST (Highly Accelerated Stress Test)
HTSL	High Temperature Storage Life
PC	Preconditioning
PD	Physical Dimensions
SD	Solderability
TC	Temperature Cycling
UHAST	Unbiased HAST (Highly Accelerated Stress Test)
WBS	Wire Bond Shear
WBP	Wire Bond Pull

6. REVISION HISTORY

Release	Date	Description
1.0	August 31st 2026	Preliminary report

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life.augmented

PRODUCT / PROCESS CHANGE NOTIFICATION

HTXA subcontractor (China) additional back-end qualification for 2Kb to 128Kb I²C EEPROM in DFN8

What is the change?
The **low densities EEPROM I²C 2Kb to 128Kb in DFN8** (CMOS F8H+ process technology) currently assembled & tested at ST Calamba (Philippines) **will also be assembled & tested at HTXA subcontractor (China)**.

Why?
The strategy of STMicroelectronics Connected Security division is to support our customers on products and service quality on a long-term basis. In line with this commitment, the qualification of the HTXA back-end assembly & test site as a second source will allow us to increase capacity and reinforce long term competitiveness.

When?
Qualified samples will be available from Week 41 / 2026.
Shipment will start from Week 49 / 2026 or earlier upon customer agreement.

How will the change be qualified?
This change is qualified using the standard STMicroelectronics Corporate Procedures for Quality and Reliability.
The intermediate reliability report RRCS2610 is available.
The final reliability report RRCS2610 will be available Week 43 / 2026.

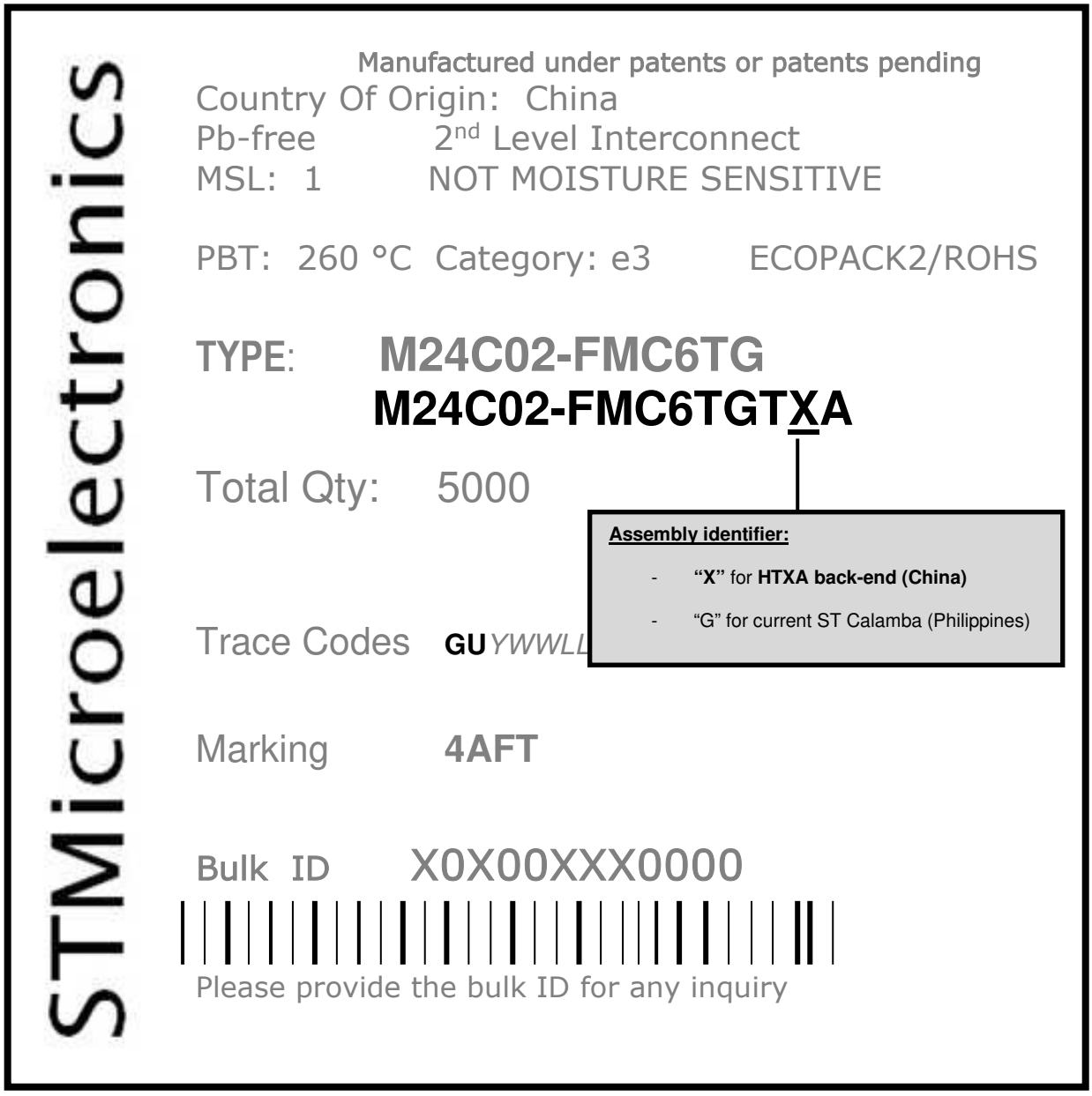
What is the impact of the change?
- **Form:** Marking change
- **Fit:** No change
- **Function:** No change

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- ***BOX LABEL MARKING***

On the BOX LABEL, the difference is visible inside the **Finished Good Part Number** where the "**Assembly plant**" identifier is "**X**" for products assembled & tested at the **additional HTXA subcontractor (China)**, this identifier being "G" for current ST Calamba (Philippines).

Example for M24C02-FMC6TG



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How can the change be seen?

- DEVICE MARKING

The difference is visible inside the trace code (*PYWW*) where the first digit *P* for the **assembly plant** identifier is "**U**" for the **additional HTXA (China) assembly & test subcontractor**, this identifier being "8" for the current ST Calamba (Philippines).

	HTXA (China)	ST Calamba (Philippines)
DFN8 Example: *M24C02-FMC6TG*	° **4AFT** **U***YWW*	° **4AFT** **8***YWW*

P = Assembly plant
Y = Last digit of the Year of Assembly
WW = Assembly Week

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Appendix A- Product Change Information

Product family / Commercial products:	2Kb to 128Kb CMOSF8H+ I²C EEPROM in DFN8
Customer(s):	All
Type of change:	Additional back-end site
Reason for the change:	Additional sourcing
Description of the change:	HTXA subcontractor (China) additional DFN8 back-end to current ST Calamba (Philippines) for 2Kb to 128Kb CMOSF8H+ I²C EEPROM
Forecast date of the change: (Notification to customer)	Week 36 / 2026
Forecast date of Qualification samples availability for customer(s):	Week 41 / 2026
Qualification Report availability:	Intermediate Reliability Evaluation Report RRCS2610 is available. Final report will be available Week 43 / 2026.
Marking to identify the changed product:	Assembly plant identifier "**U**" on DFN8 package.
Description of the qualification program:	Standard ST Microelectronics Corporate Procedures for Quality and Reliability
Estimated date of first shipment:	Week 49 / 2026

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Appendix B: concerned Commercial Part Numbers:

Commercial product	Finished Good Part number	Qualified samples availability
M24C02-FMC6TG	M24C02-FMC6TGTXA	Week 41
M24C02-RMC6TG	M24C02-RMC6TGTXA	Week 41
M24C04-FMC6TG	M24C04-FMC6TGTXA	Week 41
M24C04-RMC6TG	M24C04-RMC6TGTXA	Week 41
M24C08-FMC6TG	M24C08-FMC6TGTXA	Week 41
M24C08-RMC6TG	M24C08-RMC6TGTXA	Week 41
M24C16-FMC6TG	M24C16-FMC6TGTXA	Week 41
M24C16-RMC6TG	M24C16-RMC6TGTXA	Week 41
M24C32-FMC6TG	M24C32-FMC6TGTXA	Week 41
M24C32-FMC6TG/T	M24C32-FMC6TGTX1	Week 41
M24C64-FMC6TG	M24C64-FMC6TGTXA	Week 41
M24128-BFMC6TG	M24128BFMC6TGTXA	Week 41
M24128-BFMC6TG/T	M24128BFMC6TGTX1	Week 41

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Appendix C: BOM comparison:

	HTXA subcon	ST Calamba
Leadframe	**Matte Tin post plating**	PPF 3-layer NiPdAu
Molding compound	**SUMITOMO G770**	HITACH CEL 9240
Glue die-attach	**HITACHI EN 4900** (PFAS free)	ABLESTIK QMI519
Wire	**CuPd**	Cu

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Document Revision History

Date	Rev.	Description of the Revision
July 02, 2026	1.00	Christian POLI - First draft creation

Source Documents & Reference Documents

Source document Title	Rev.:	Date:

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